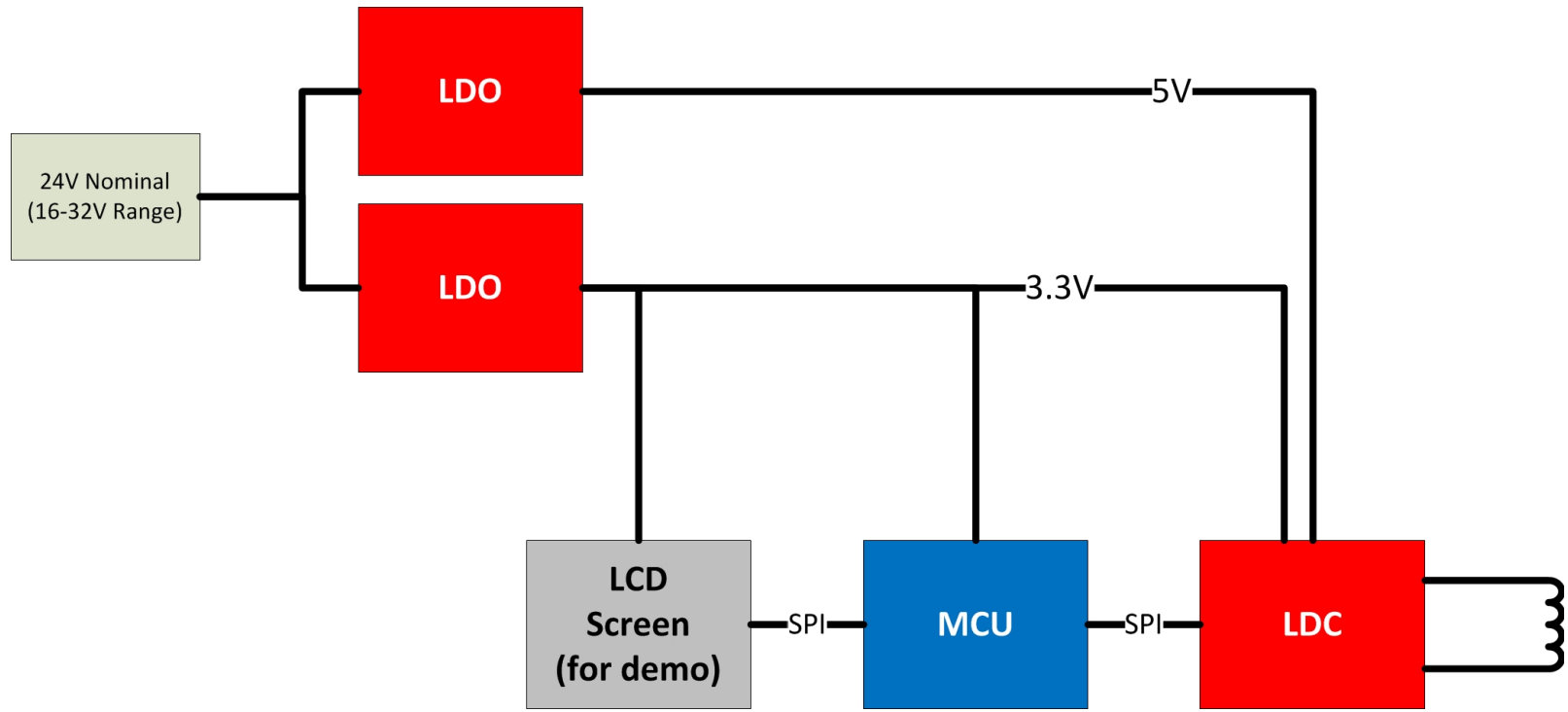


# TIDA-00215

## Distance & Weight Measurement Using Inductive Sensing

Revision History	
Revision	Notes

### System Block Diagram



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Designed for: Public Release		Mod. Date: 6/11/2014	
Project Title: Distance & Weight Measurement Using Inductive Se			
Number: ISE4008	Rev: E2	Sheet Title:	Sheet: 1 of 3
SVN Rev: Not in version control	Assembly Variant: 001	File: ISE4008 Cover Sheet SchDoc	Size: B
Drawn By:	Engineer: Evan Cornell	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	<a href="http://www.ti.com">http://www.ti.com</a>
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H1 NY PMS 440 0025 PH    H2 NY PMS 440 0025 PH    H3 NY PMS 440 0025 PH    H4 NY PMS 440 0025 PH    H8 NY PMS 440 0025 PH    H10 NY PMS 440 0025 PH



~~DNP~~ HD1    ~~DNP~~ HD2    ~~DNP~~ HD3    ~~DNP~~ HD4    ~~DNP~~ HD5    ~~DNP~~ HD6

PCB Number: ISE4008  
PCB Rev: E2

PCB  
LOGO  
Texas Instruments

Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1  
PCB Label

Serial # - Production Date

ZZ1  
Label Assembly Note

This Assembly Note is for PCB labels only

ZZ2  
Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ5  
Assembly Note

Place SH-J1 on J6 and SH-J2 on J7 during assembly.

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Designed for: Public Release		Mod. Date: 5/12/2014	
Number: ISE4008	Rev: E2	Project Title: Distance & Weight Measurement Using Inductive Se	
S/N Rev: Not in version control		Assembly Variant: 001	Sheet: 3 of 3
Drawn By: Evan Cornell	File: Hardware_ANSI-B_SchDoc	Size: B	
Engineer: Evan Cornell	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	http://www.ti.com	



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